

US00D794582S

(12) **United States Design Patent** (10) **Patent No.:** **US D794,582 S**
Zhang et al. (45) **Date of Patent:** **** Aug. 15, 2017**

(54) **LED CHIP**

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(**) Term: **15 Years**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**

USPC D13/180; D26/1
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;
H01L 27/156; H01L 31/02; H01L 33/00;
H01L 33/04; H01L 33/08; H01L 33/10;
H01L 33/20; H01L 33/38; H01L 33/42;
H01L 33/48; H01L 33/483; H01L 33/486
See application file for complete search history.

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(Continued)

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(57) **CLAIM**

The ornamental design for an LED chip, as shown and described.

DESCRIPTION

FIG. 1 is a 3D view of a LED chip according to an embodiment of the present disclosure in which the cover plate is transparent and the holes penetrate through the cover plate and expose the electrode;

FIG. 2 is another 3D view of the LED chip according to the embodiment of the present disclosure;

FIG. 3 is a top view of the LED chip according to the embodiment of the present disclosure;

FIG. 4 is a left-side view of the LED chip shown in FIG. 3;

FIG. 5 is a right-side view of the LED chip shown in FIG. 3;

FIG. 6 is a front-side view of the LED chip shown in FIG. 3;

FIG. 7 is a rear-side view of the LED chip shown in FIG. 3;

FIG. 8 is a bottom view of the LED chip shown in FIG. 3;

FIG. 9 is a 3D view of a LED chip according to another embodiment of the present disclosure;

FIG. 10 is another 3D view of the LED chip according to the another embodiment of the present disclosure;

FIG. 11 is a top view of the LED chip according to the another embodiment of the present disclosure;

FIG. 12 is a left-side view of the LED chip shown in FIG. 11;

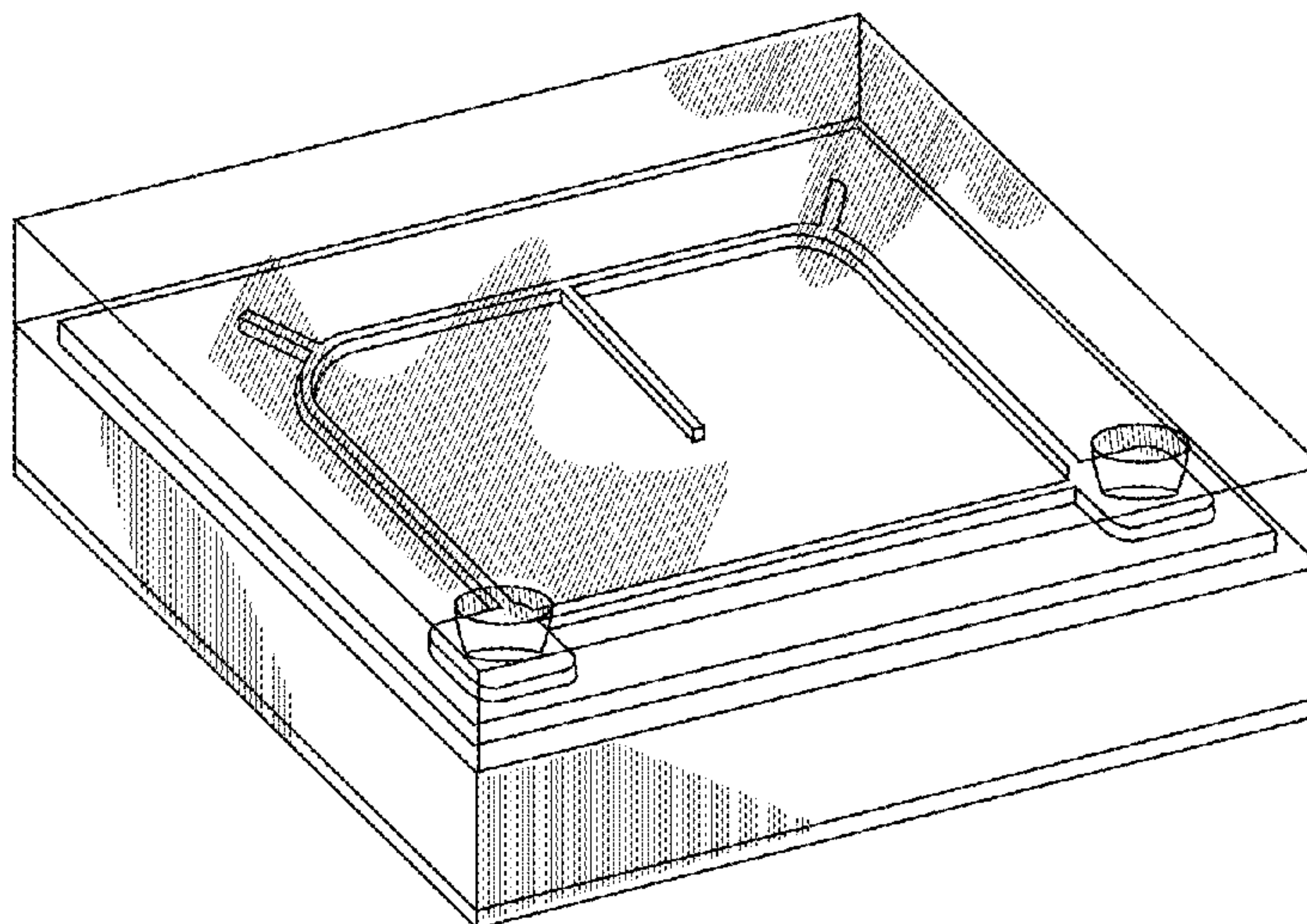
FIG. 13 is a right-side view of the LED chip shown in FIG. 11;

FIG. 14 is a front-side view of the LED chip shown in FIG. 11;

FIG. 15 is a rear-side view of the LED chip shown in FIG. 11; and,

FIG. 16 is a bottom view of the LED chip shown in FIG. 11.

1 Claim, 8 Drawing Sheets



(56)

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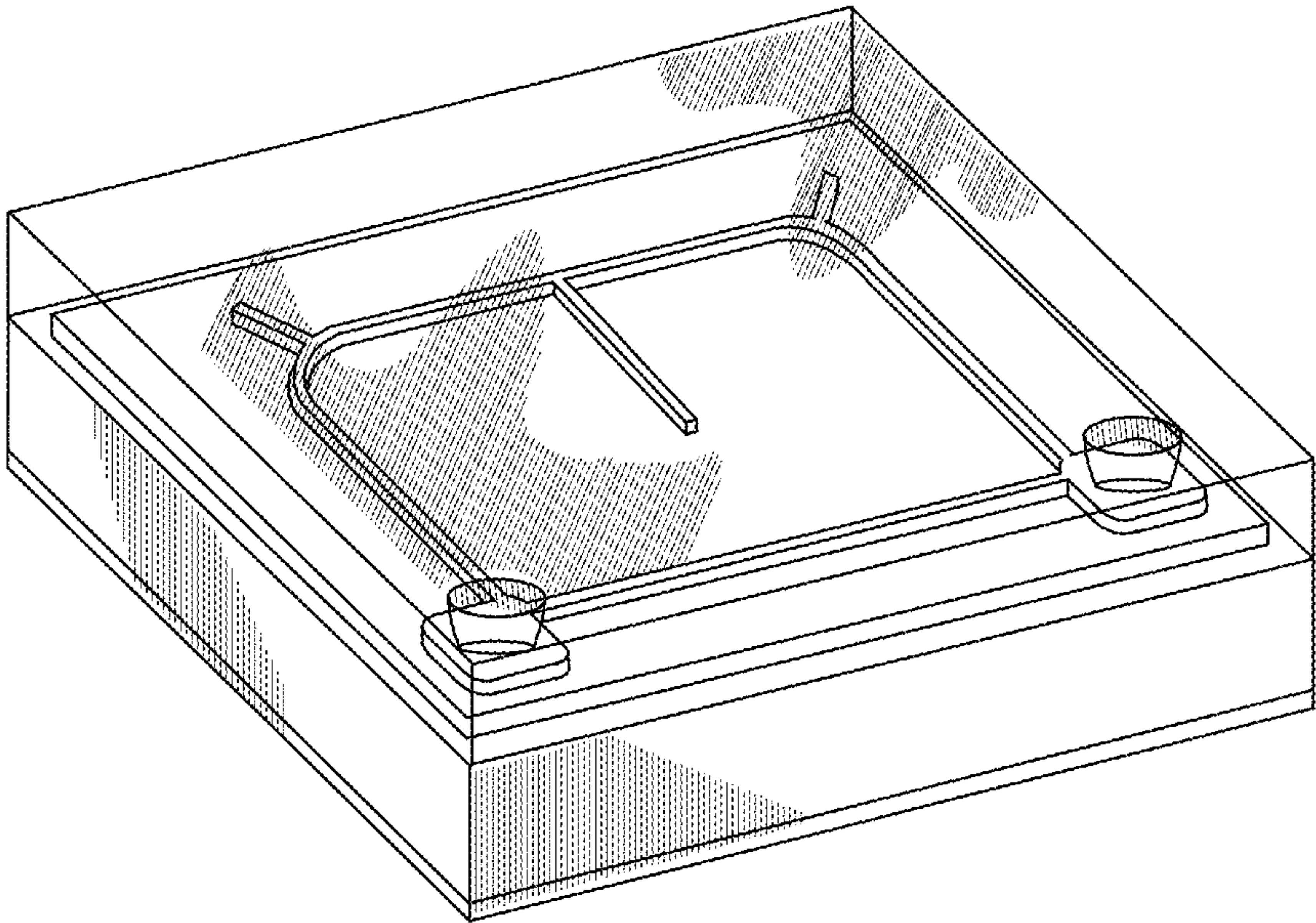


FIG. 1

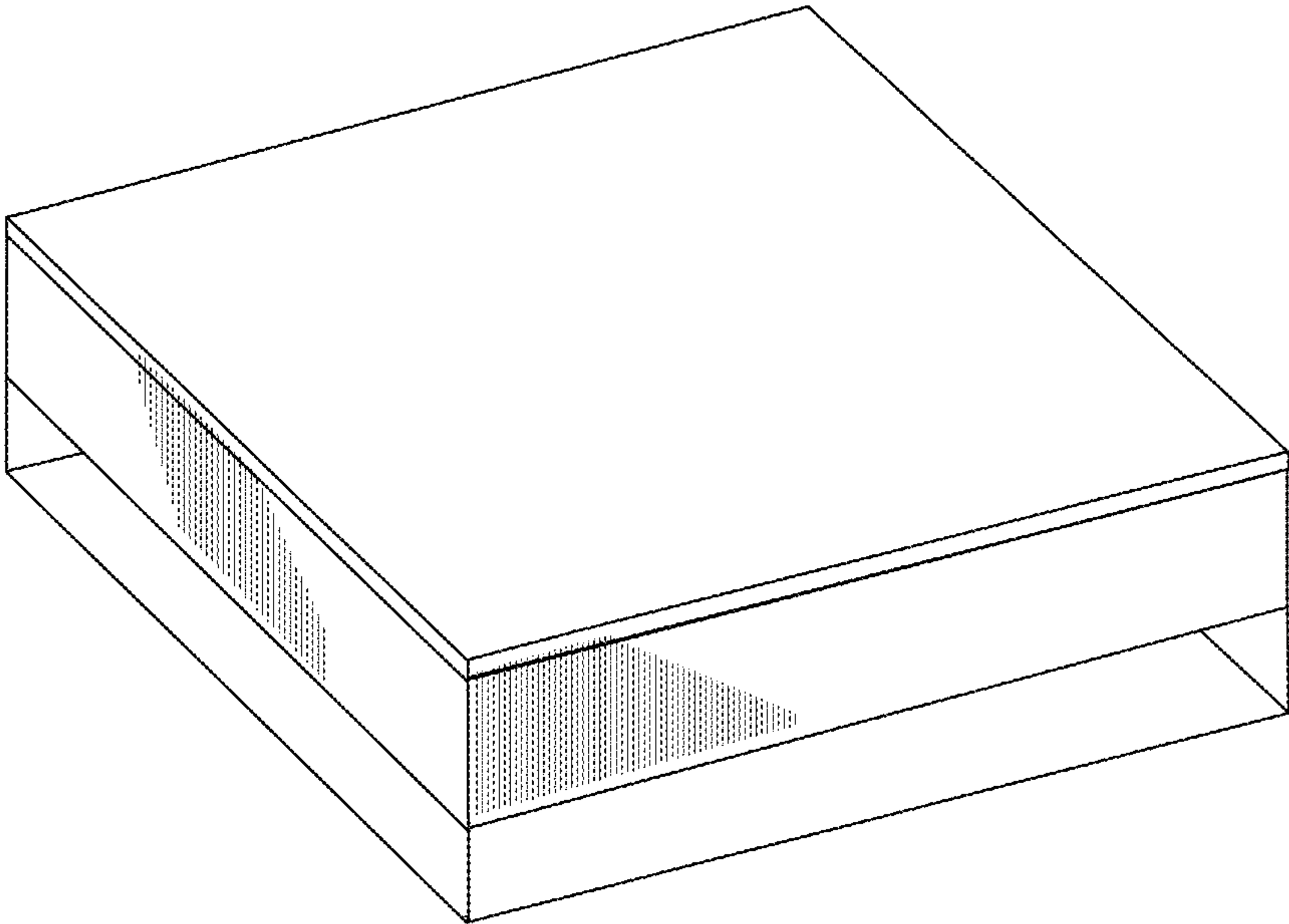


FIG. 2

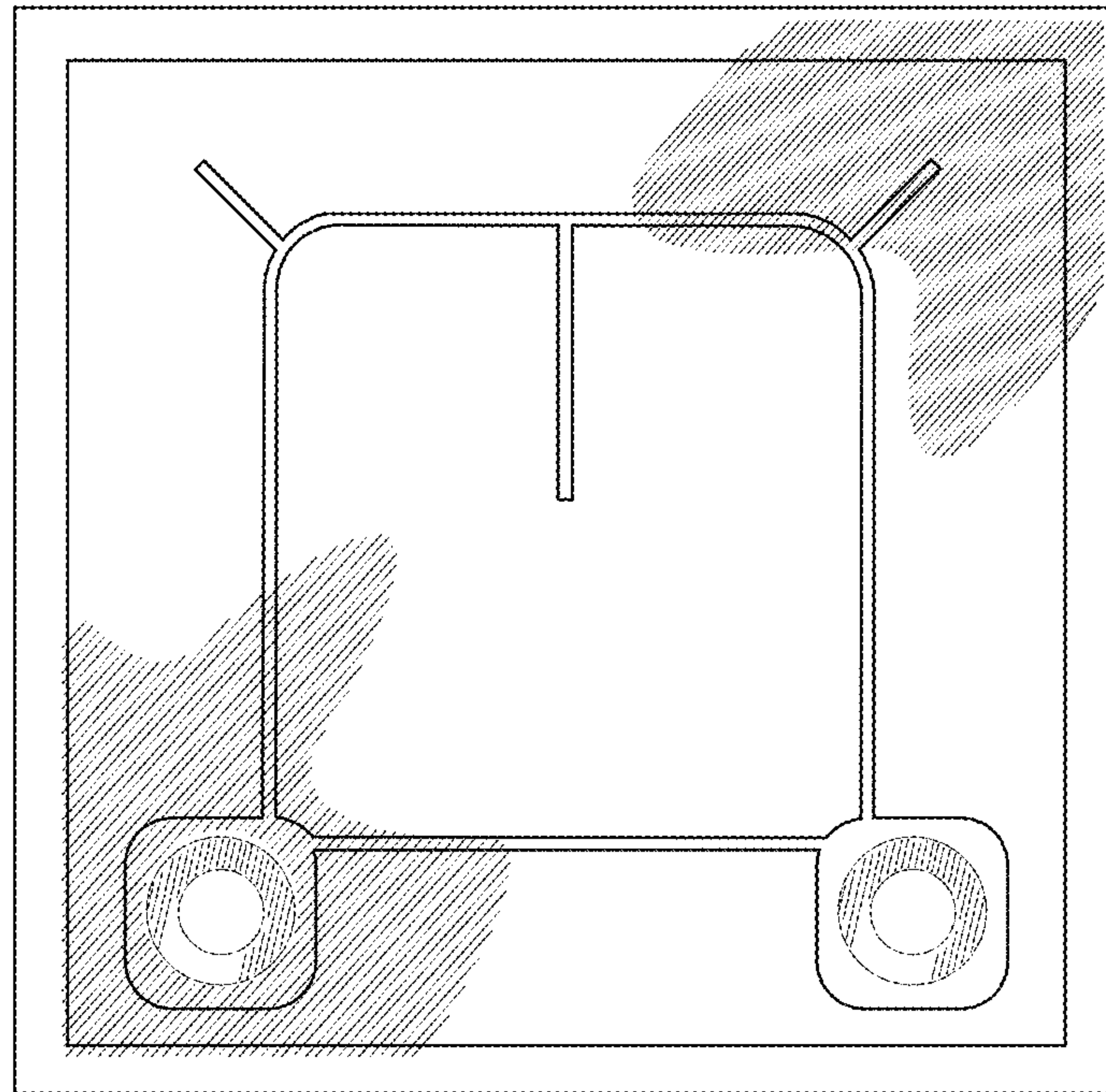


FIG. 3

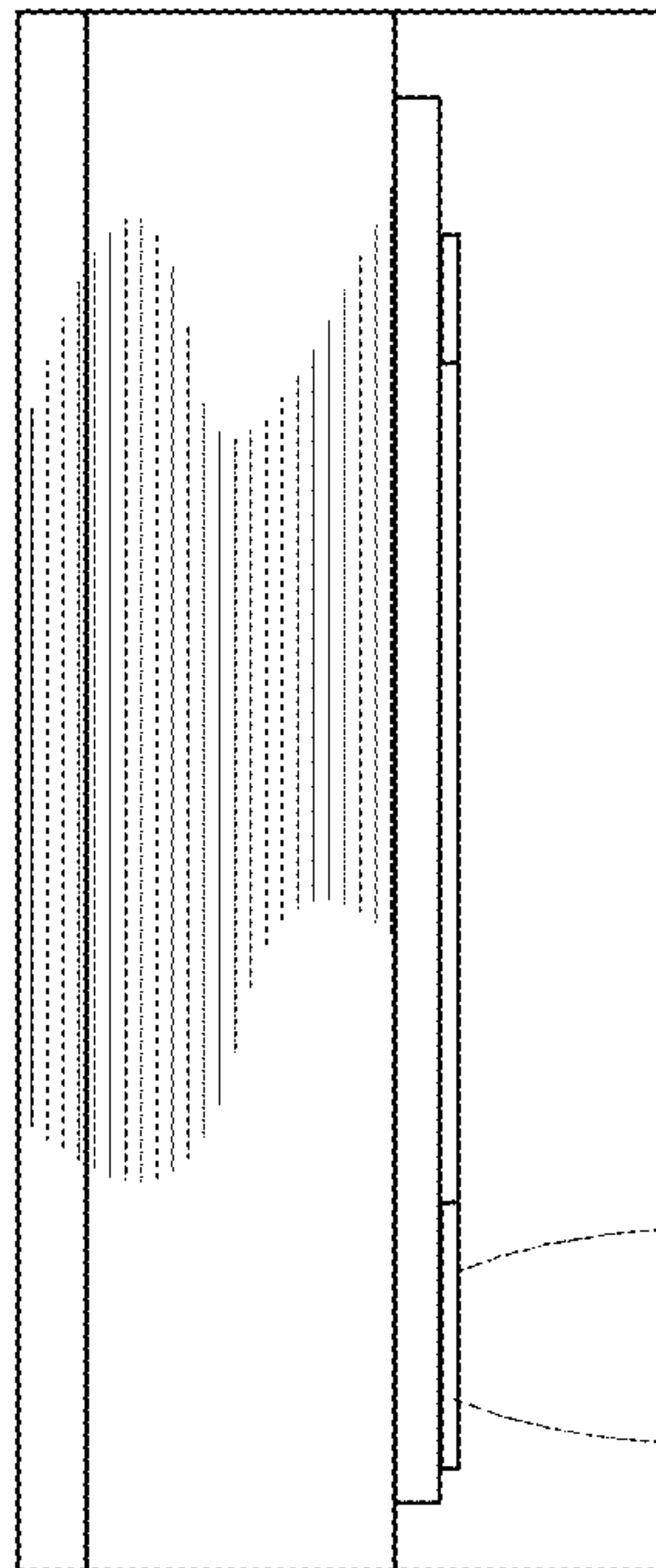


FIG. 4

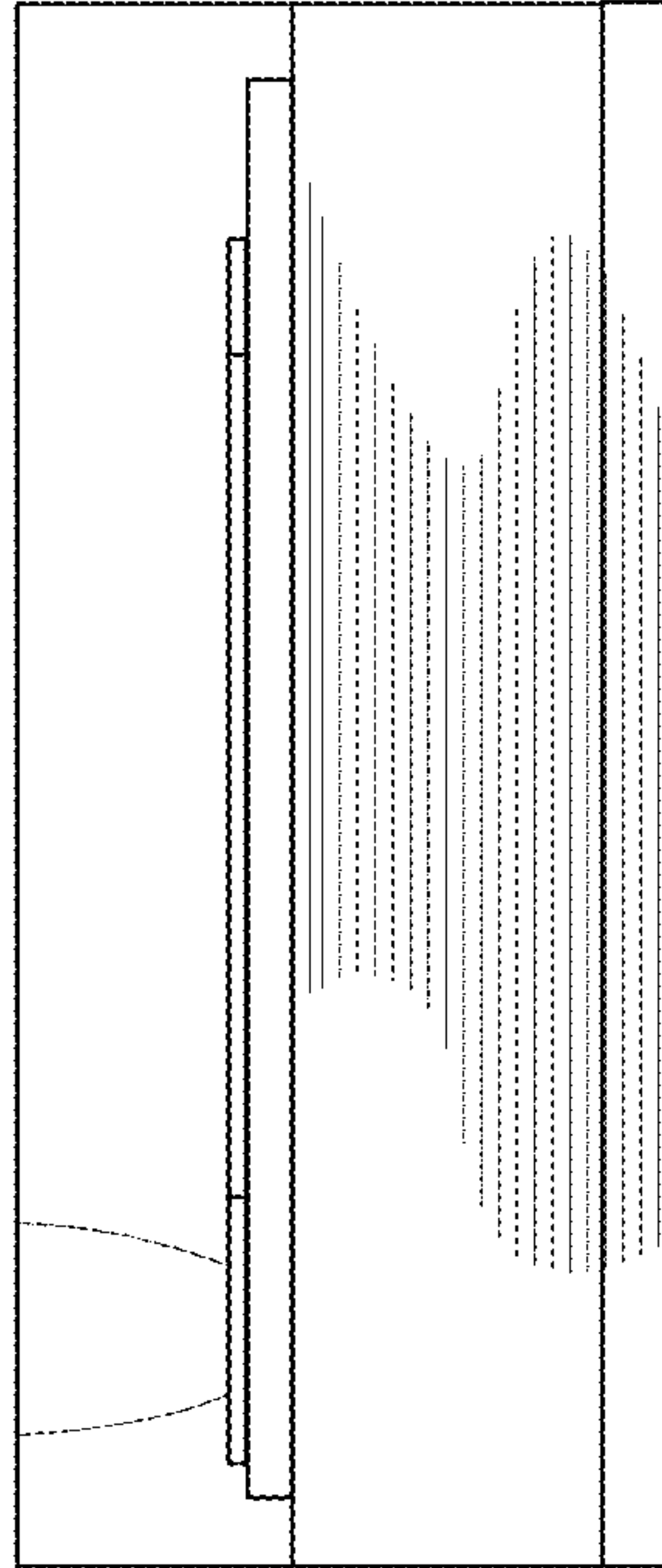


FIG. 5

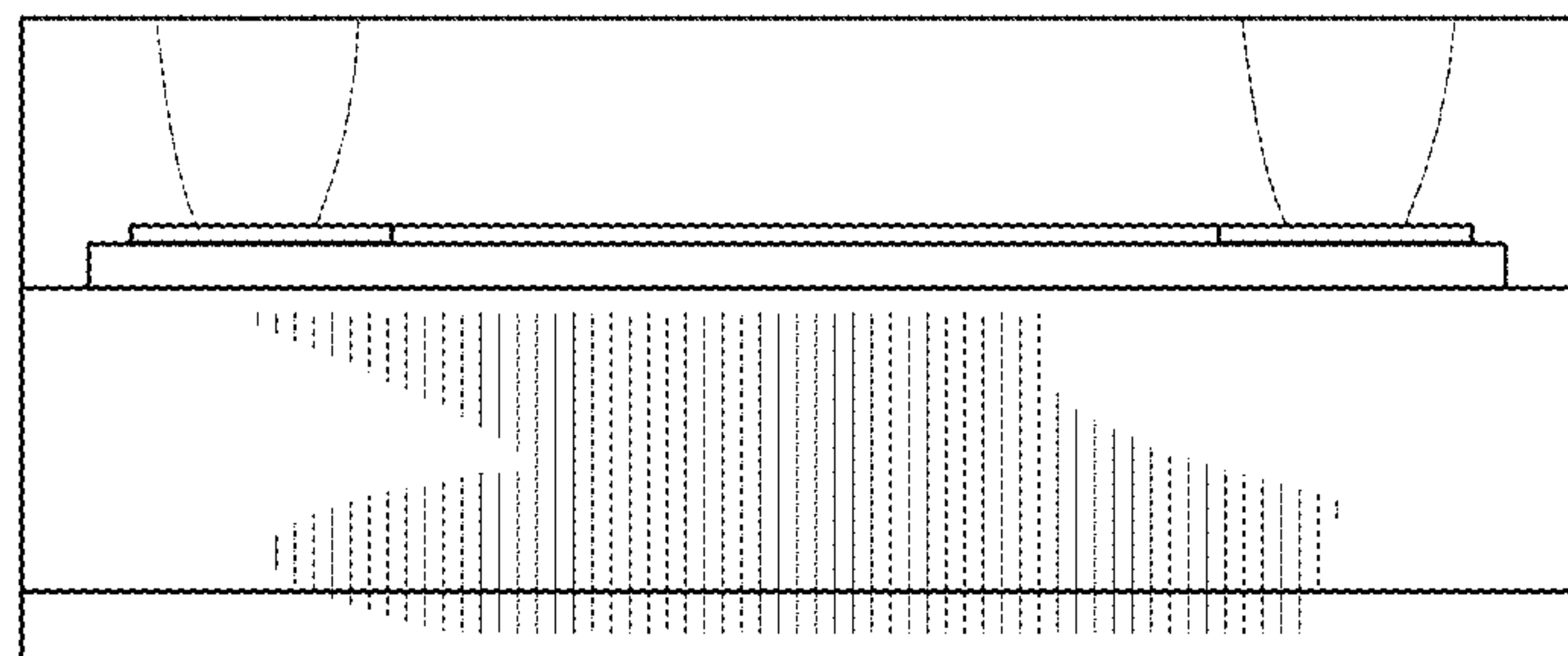


FIG. 6

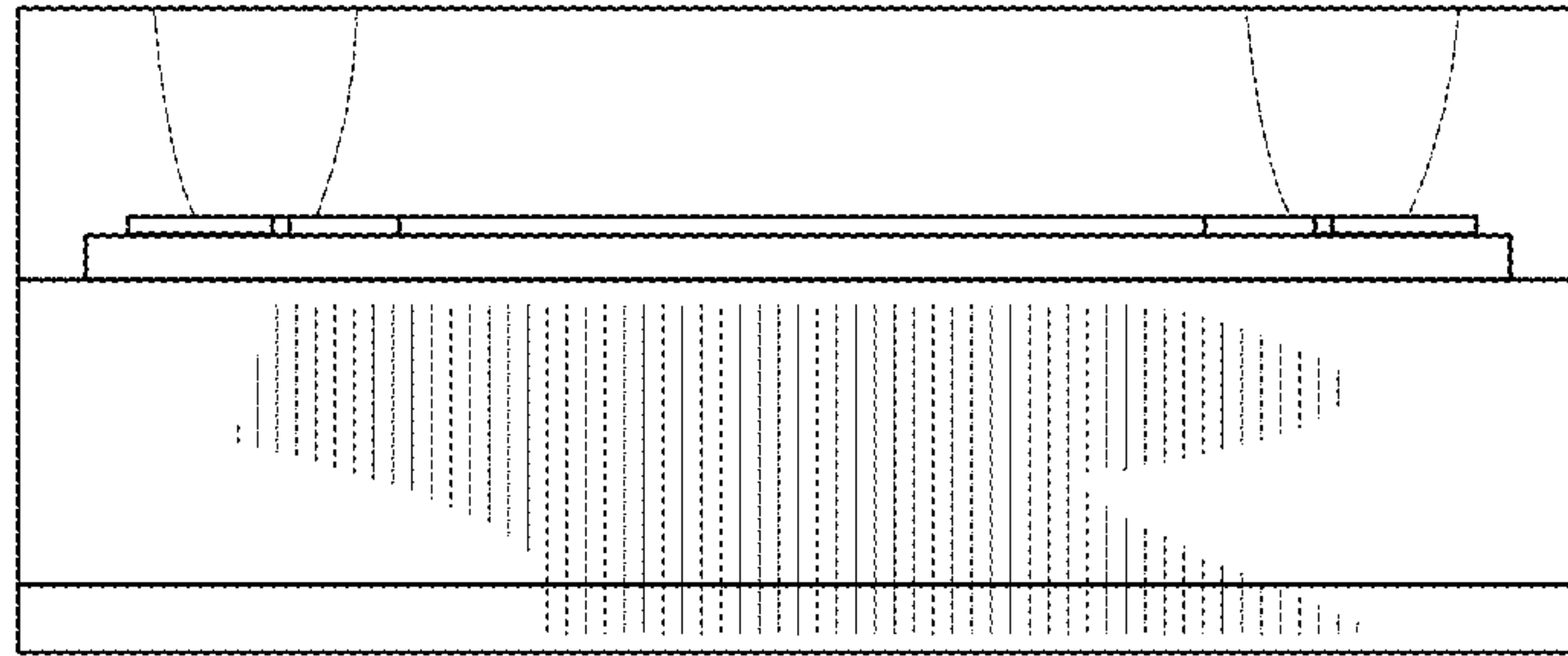


FIG. 7



FIG. 8

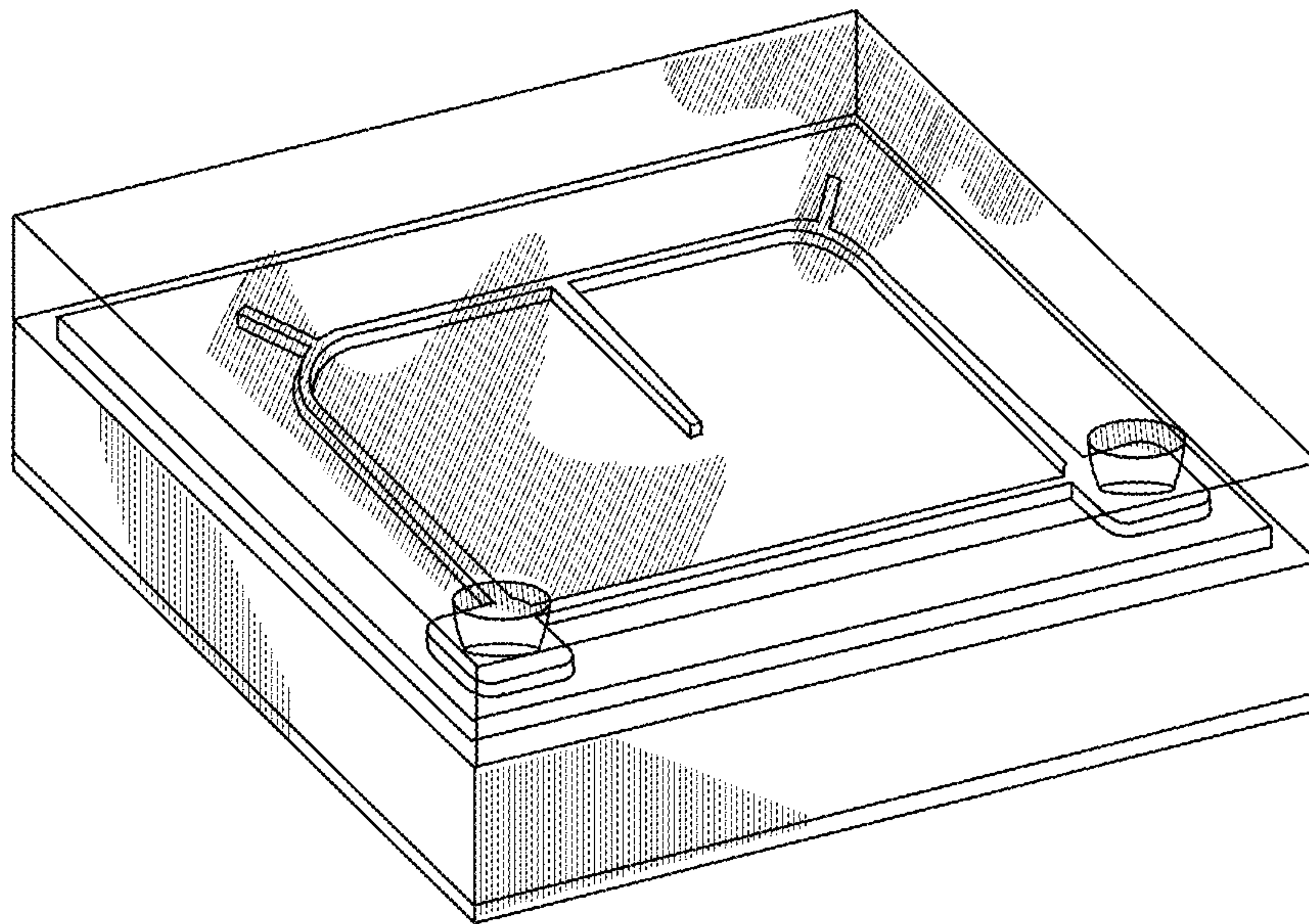


FIG. 9

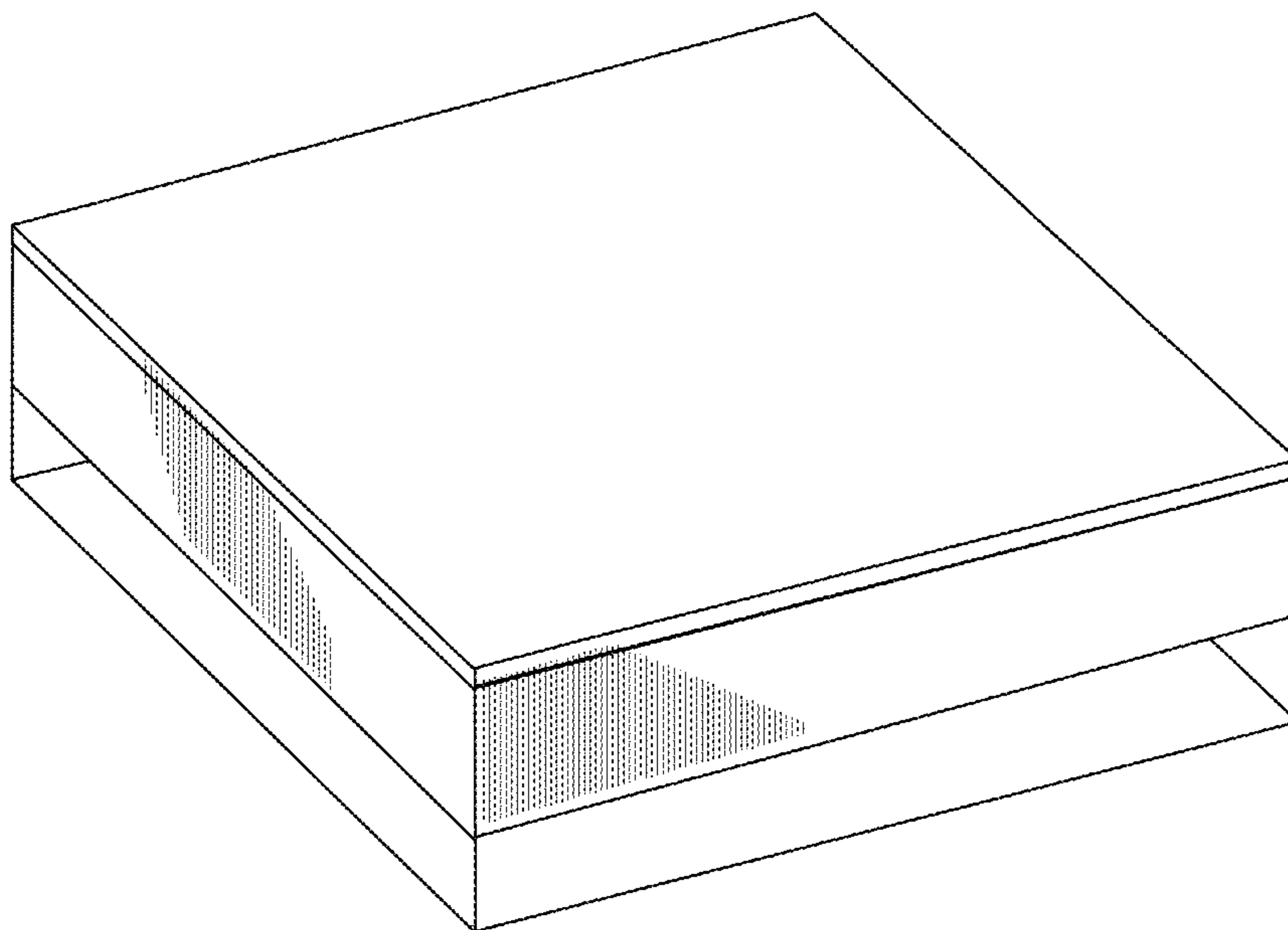


FIG. 10

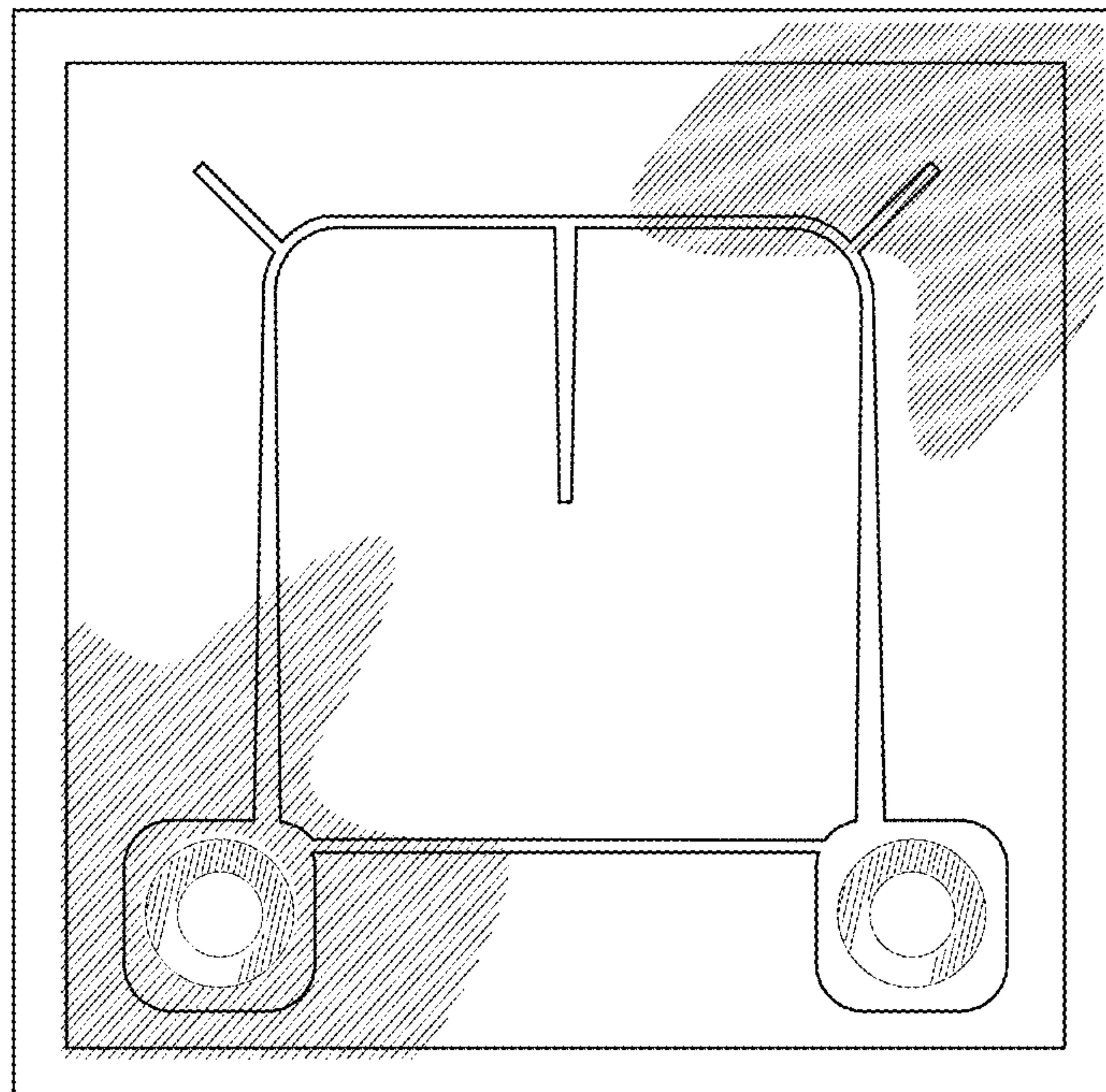


FIG. 11

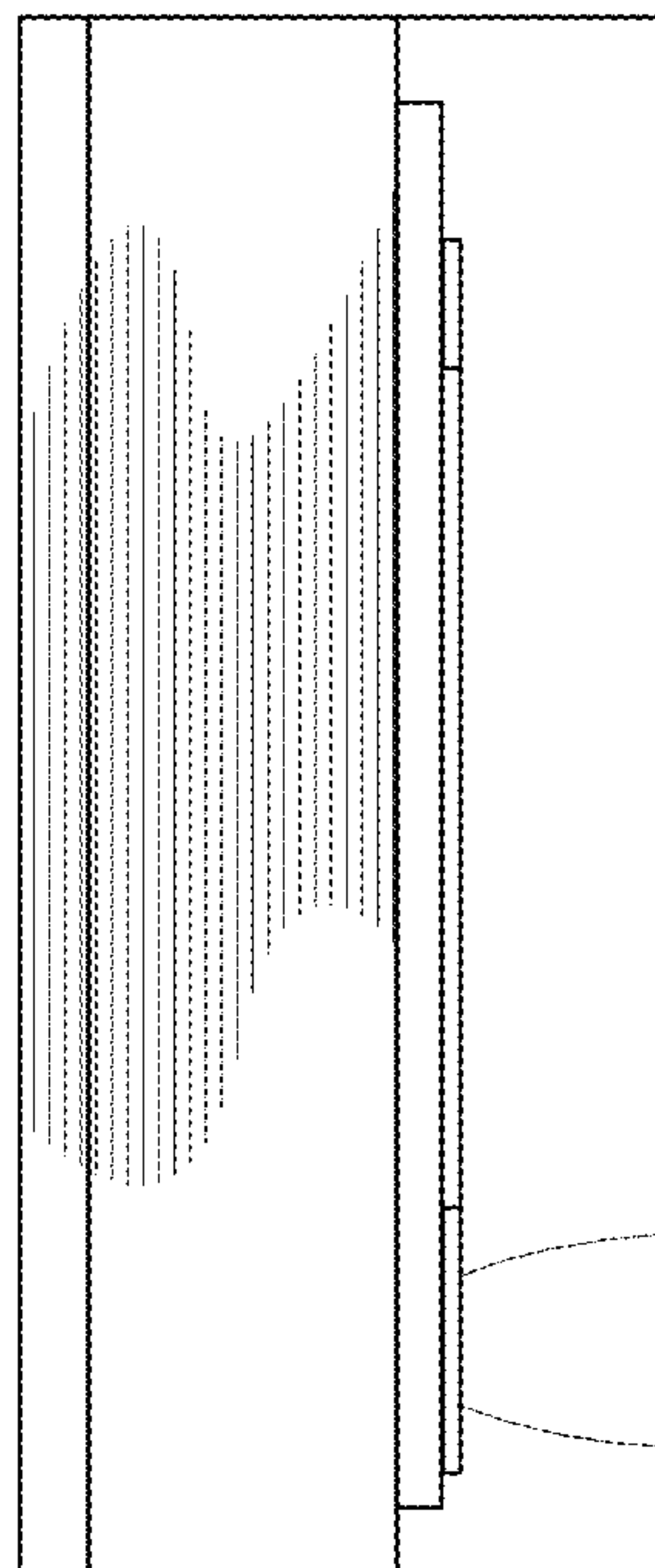


FIG. 12

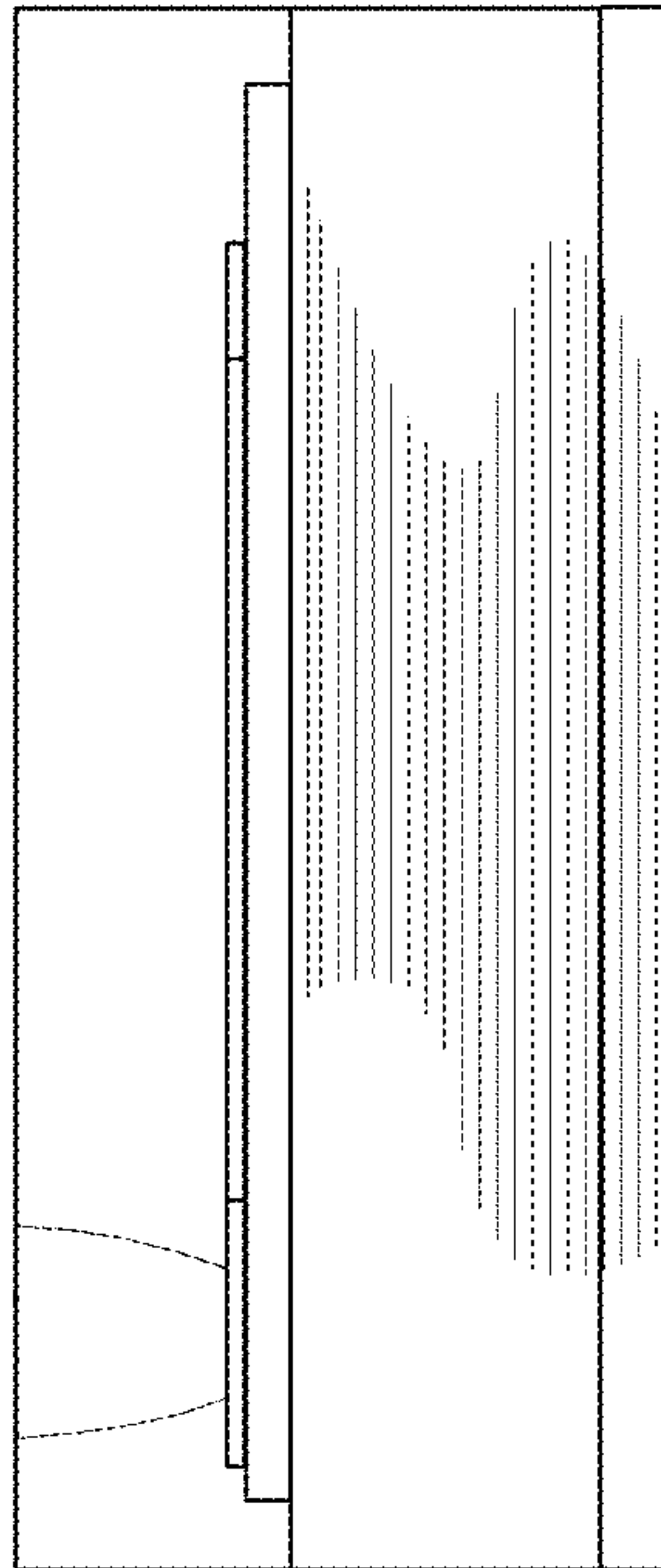


FIG. 13

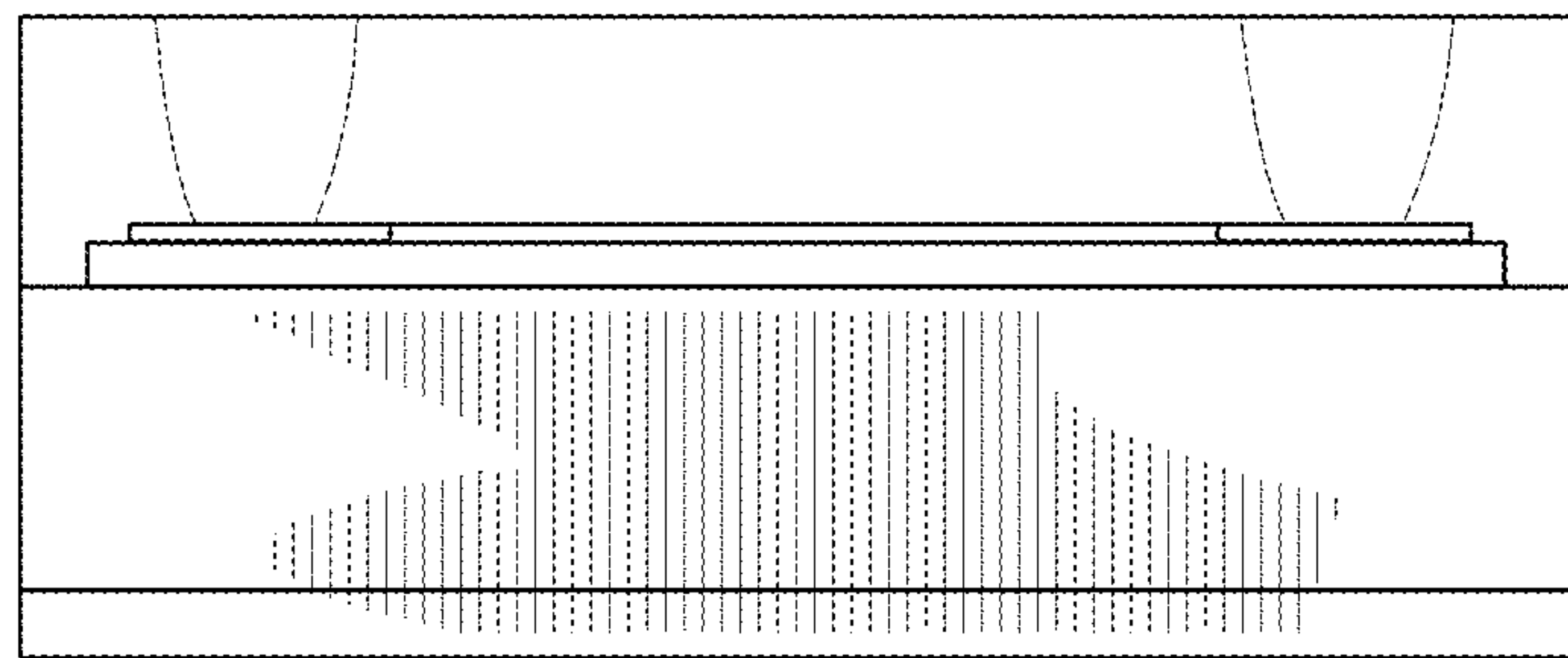


FIG. 14

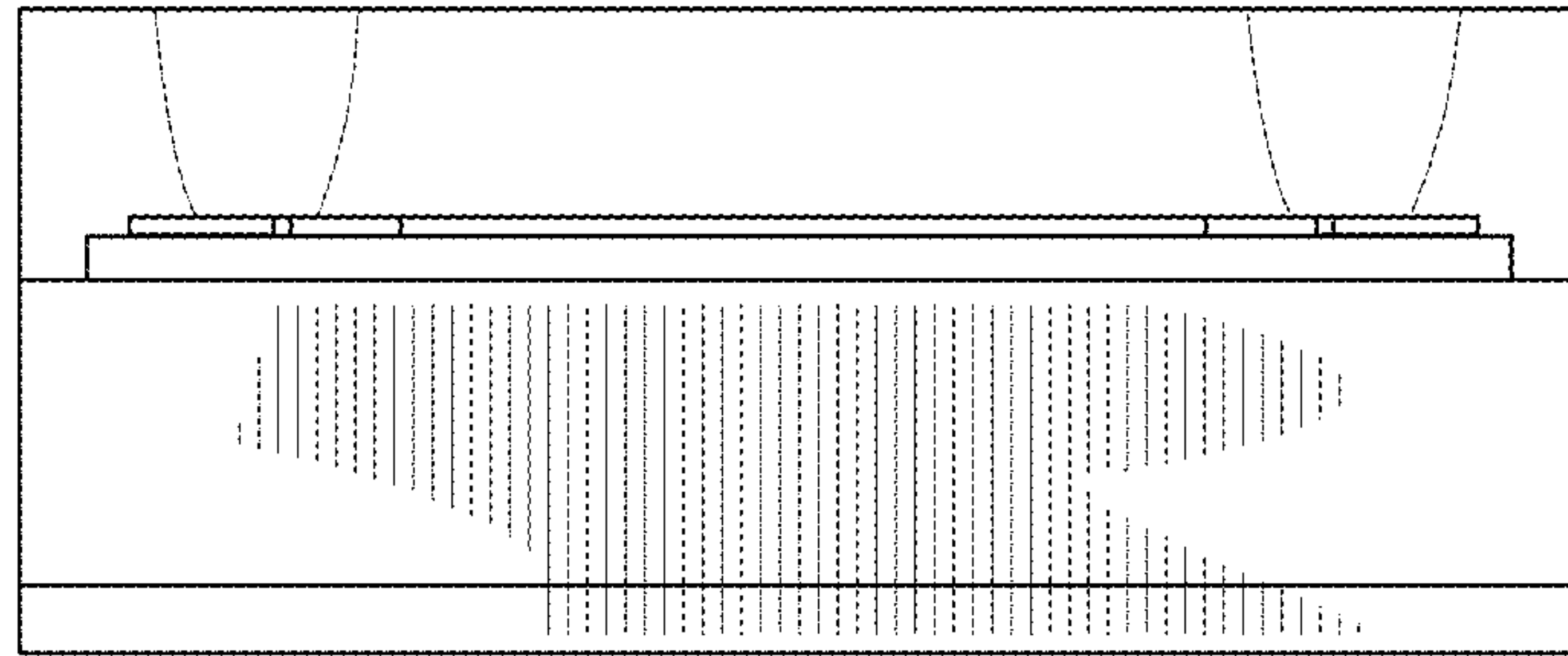


FIG. 15

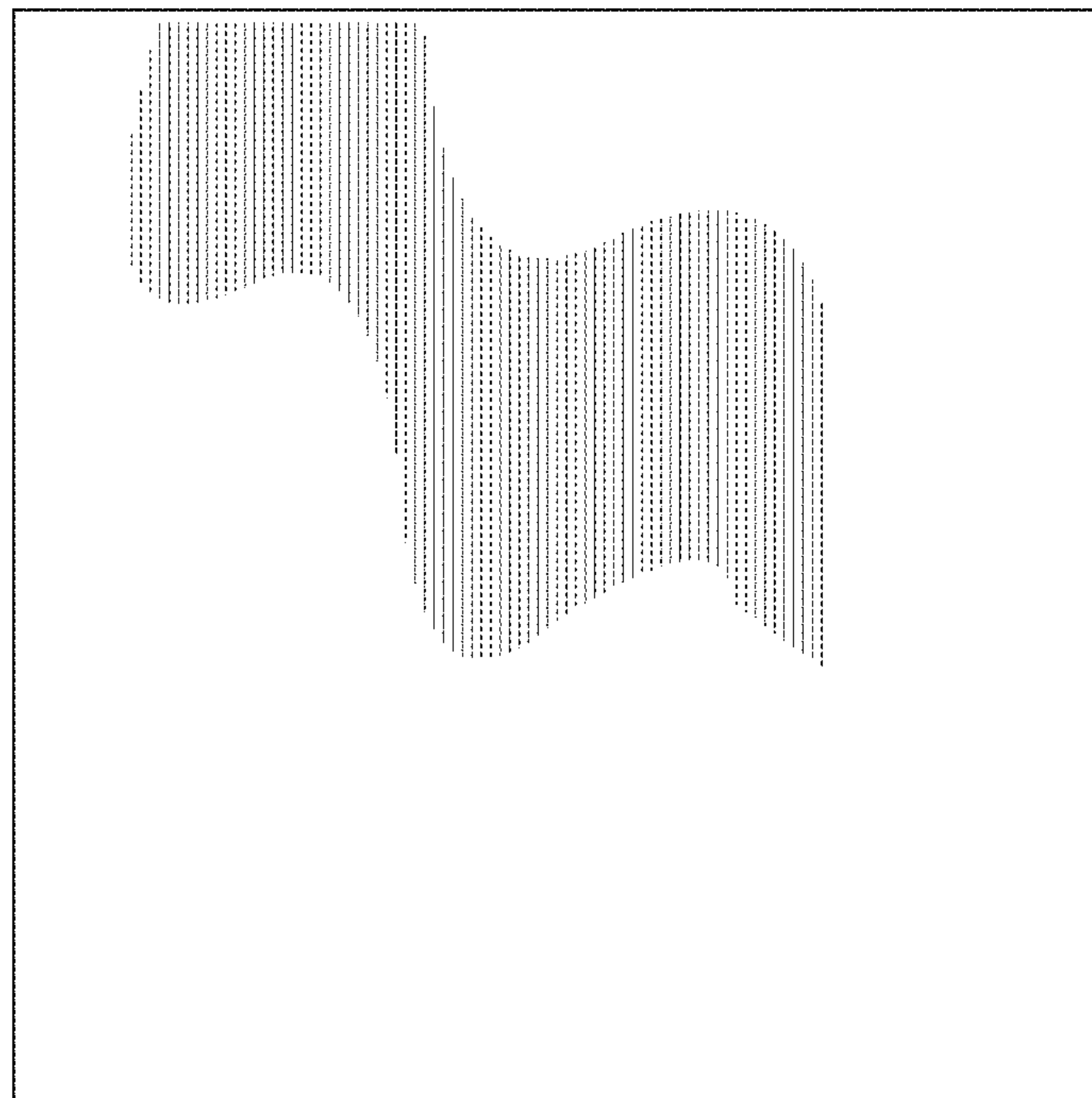


FIG. 16